

ABSTRACT

A pasting method and a pasting apparatus hold a thin plate 1 and a planar member 2 in high flatness respectively on a first holding member 44 and a second holding member 44, a main controller 40a controls a moving mechanism 45 and a parallelism adjusting mechanism 52 on the basis of information provided by position recognizing mechanisms 33 and 34 to align the thin plate 1 and the carrying member 2 with each other in a predetermined positional relation. The main controller 40a controls a moving mechanism 45 so as to move the thin plate 1 and the carrying member 2 relative to each other in a state where a liquid-phase liquid crystal wax heated by a heater 49 is held between the thin plate 1 and the carrying member 2 to spread the liquid-phase liquid crystal wax over the entire surfaces of the thin plate 1 and the carrying member 2. Thus the thin plate 1, such as a semiconductor wafer or a metal foil, can be accurately, surely and efficiently pasted to the carrying member 2, and the thin plate 1 pasted to the carrying member 2 can be readily separated from the carrying member 2.